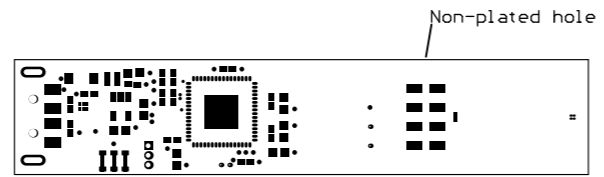
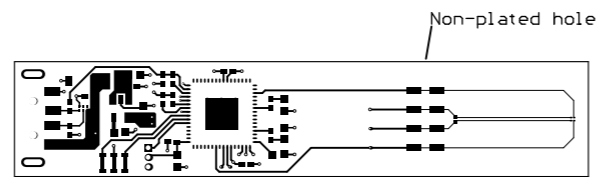


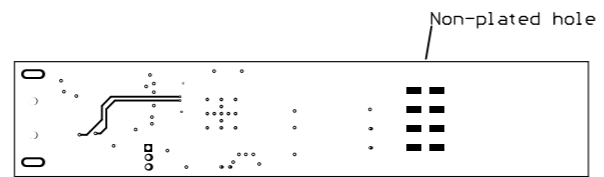
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 1/20/2015 11:41:25 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 1/20/2015 11:41:26 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 1/20/2015 11:41:26 AM	TEXAS INSTRUMENTS	

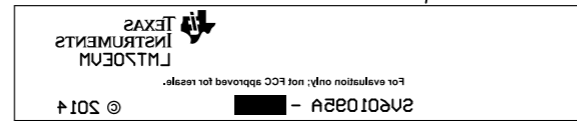


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 1/20/2015 11:41:27 AM	TEXAS INSTRUMENTS	

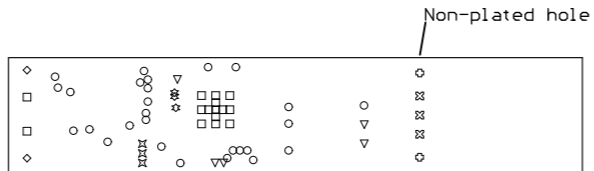


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 1/20/2015 11:41:27 AM	TEXAS INSTRUMENTS	

Non-plated hole



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 1/20/2015 11:41:28 AM	TEXAS INSTRUMENTS	

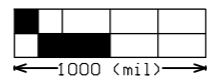
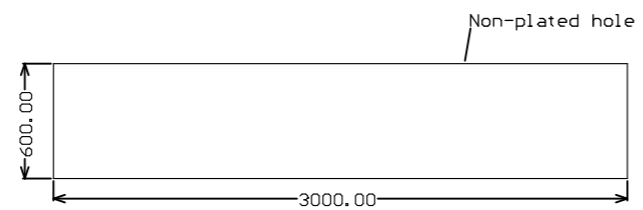


Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
⊗	3	7mil (0.178mm)			PTH	Round
□	13	7.874mil (0.2mm)			PTH	Round
▽	5	8mil (0.203mm)			PTH	Round
○	27	10mil (0.254mm)			PTH	Round
⊗	3	25.591mil (0.65mm)			PTH	Round
□	2	43.307mil (1.1mm)			NPTH	Round
◇	2	30mil (0.762mm)	98.425mil (2.5mm)	68.425mil (1.738mm)	PTH	Slot
⊗	3	31mil (0.787mm)	84mil (2.134mm)	53mil (1.346mm)	NPTH	Slot
◇	2	31mil (0.787mm)	124mil (3.15mm)	93mil (2.362mm)	NPTH	Slot
60 Total						

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
 Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 1/20/2015 11:41:28 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:SU601095	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 1/20/2015 11:41:29 AM	TEXAS INSTRUMENTS	

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